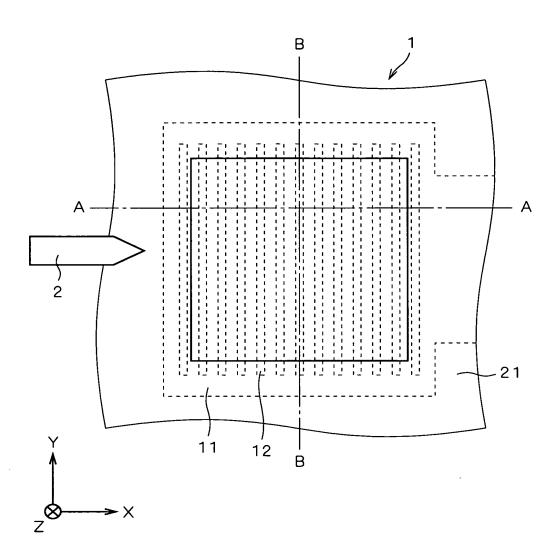
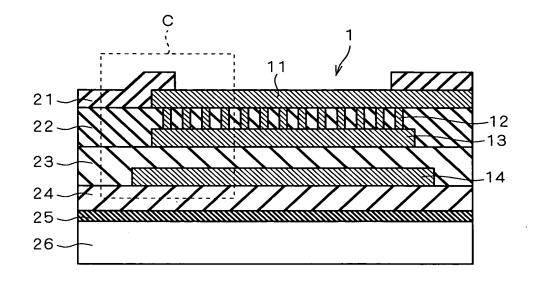
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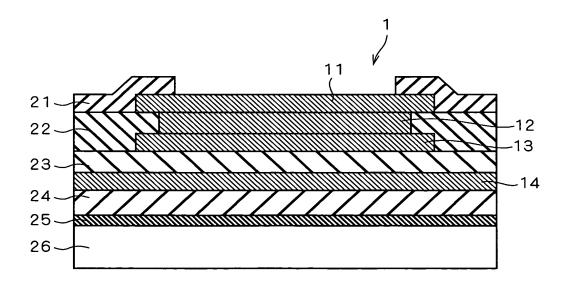
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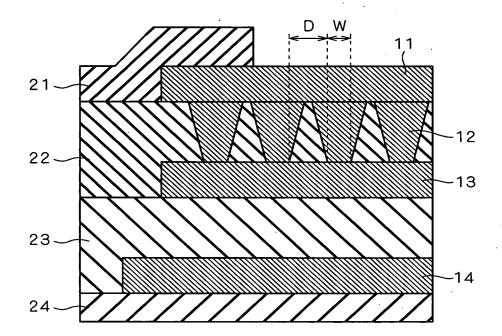


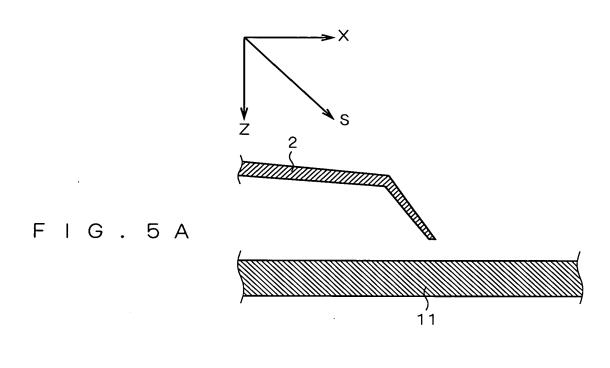
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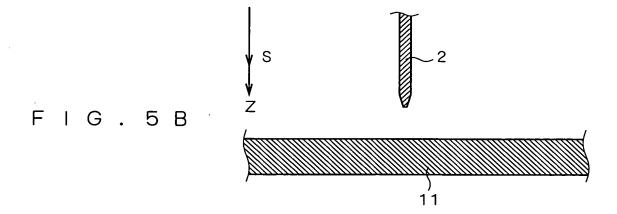


F I G . 3





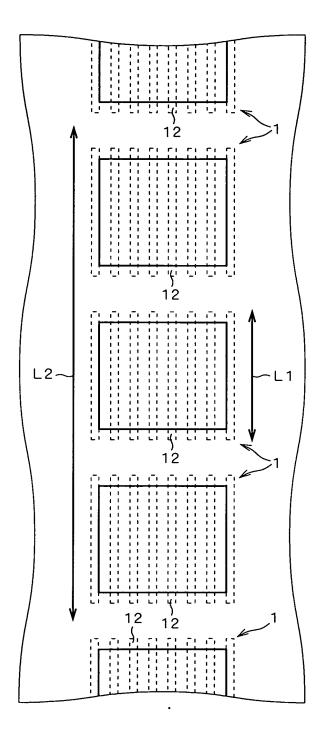


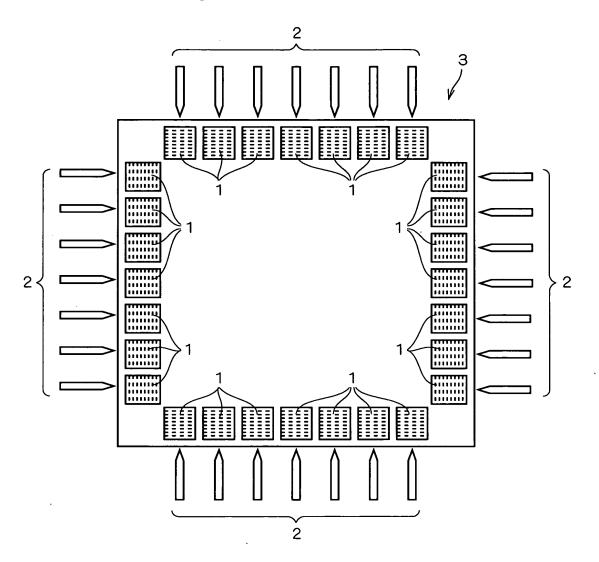


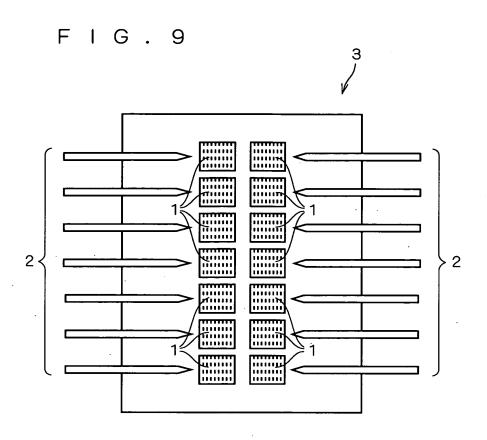
		AMOUNT OF OD (μm)	NUMBER OF TIMES OF PROBING			
			ONCE	5 TIMES	7 TIMES	10 TIMES
1	CONVENTIONAL STRUCTURE (LARGE CALIBER VIA HOLE)	50 80 100	000	000	00x	0 × ×
2	EMBODIMENT 1 (CONTACTING AT RIGHT ANGLE TO SECOND METAL)	50 80 100	000	000	00×	××O
3	EMBODIMENT 1 (CONTACTING IN PARALLEL WITH SECOND METAL)	50 80 100	000	×00	0 × ×	×××
4	EMBODIMENT 2 (STRESS SIMULATION)	50 80 100	000	000	000	0××
5	EMBODIMENT 4 (COMBINATION STRUCTURE WITH EMBODIMENT 1)	50 80 100	000	000	000	000

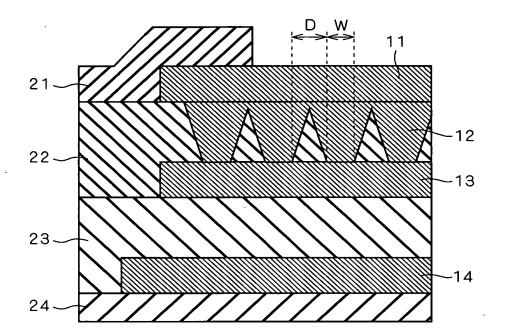
O: NO CRACK

× : CRACK GENERATION

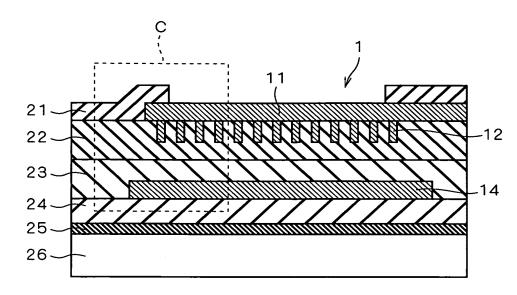




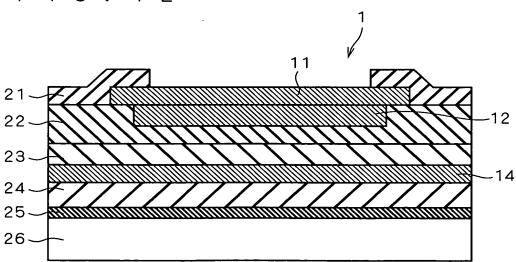




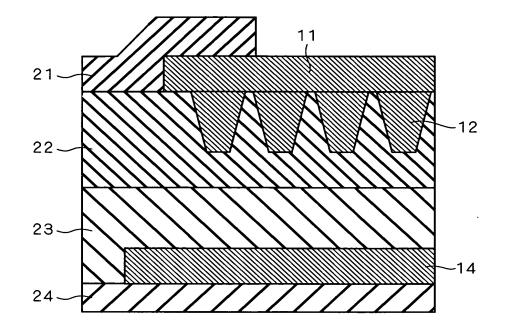
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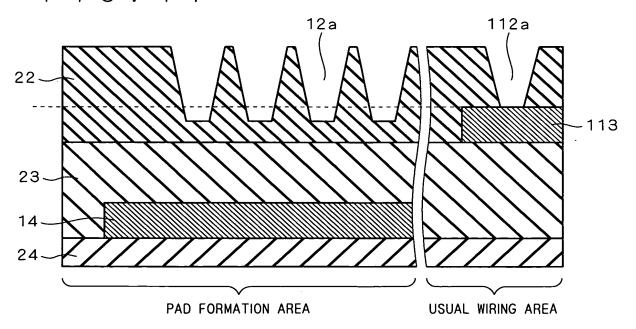
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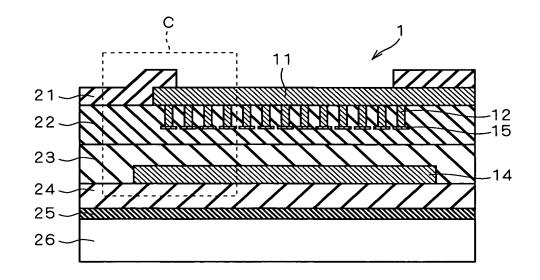
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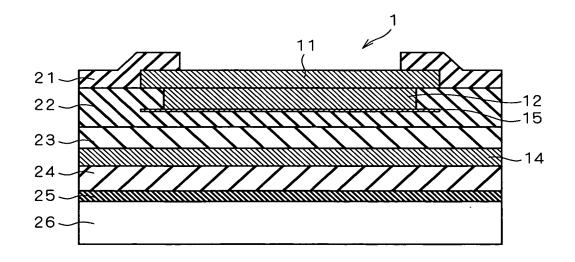
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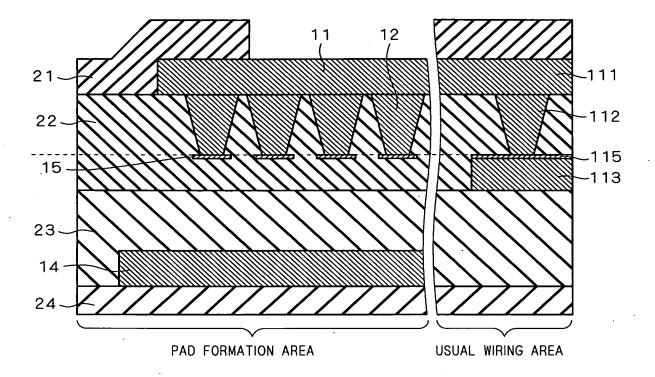
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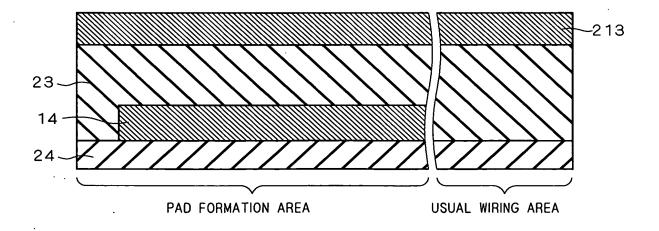
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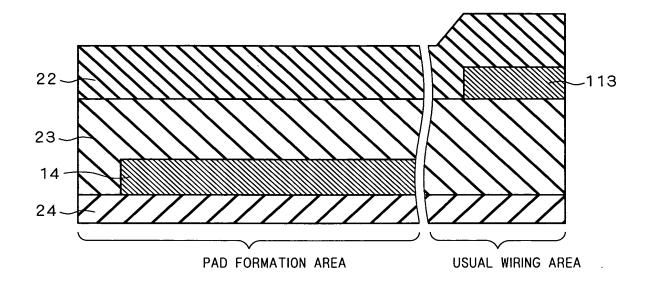


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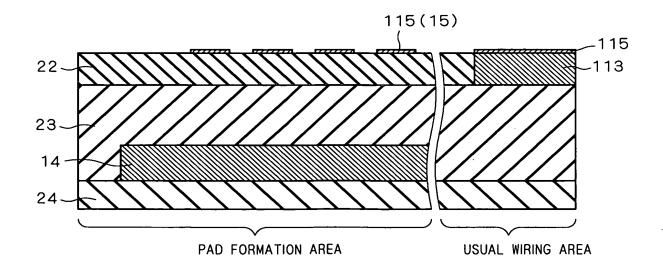


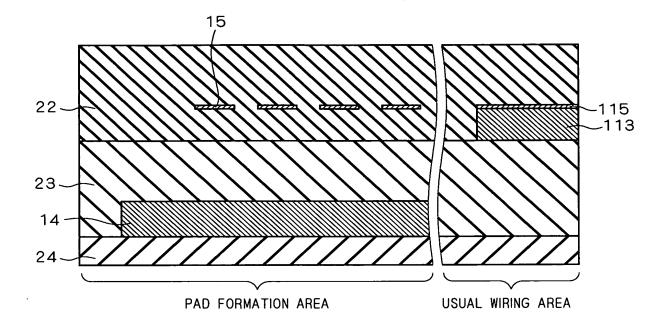
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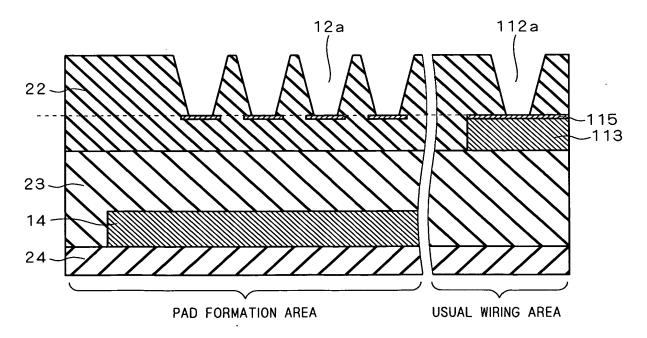


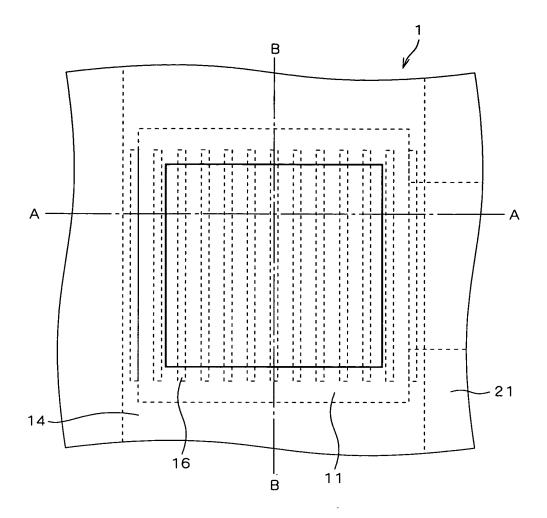
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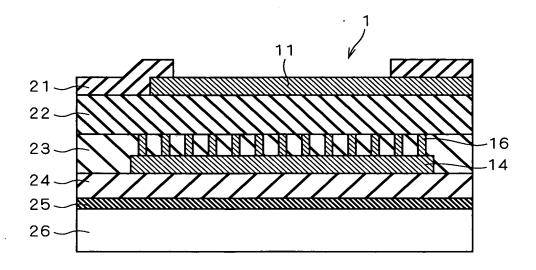


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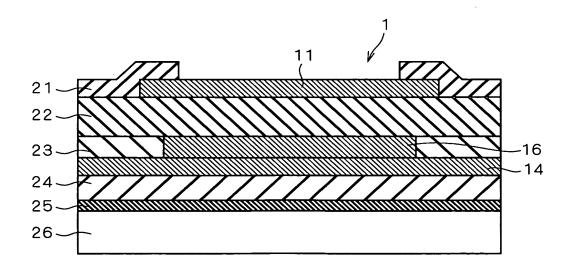




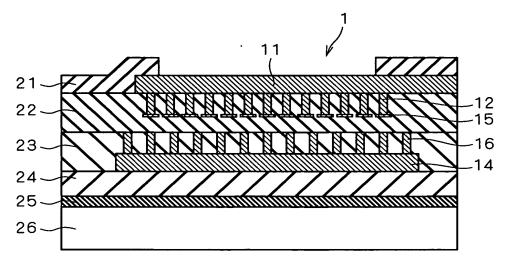
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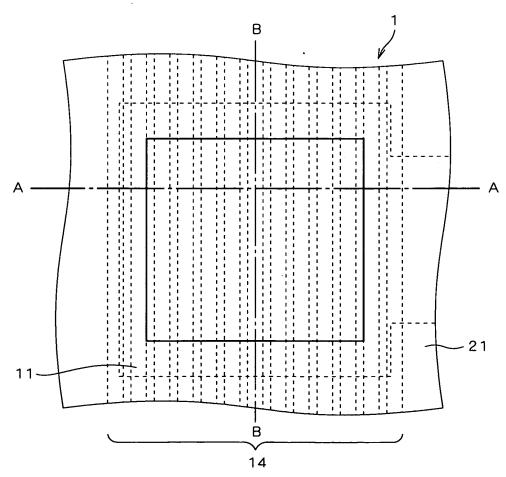
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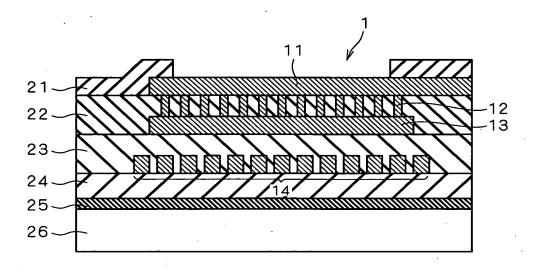
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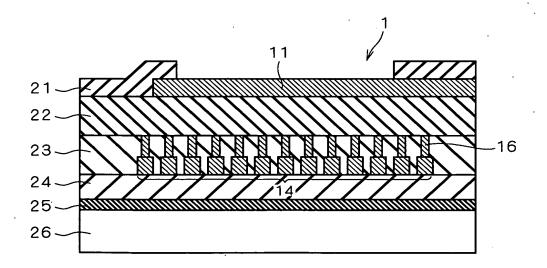
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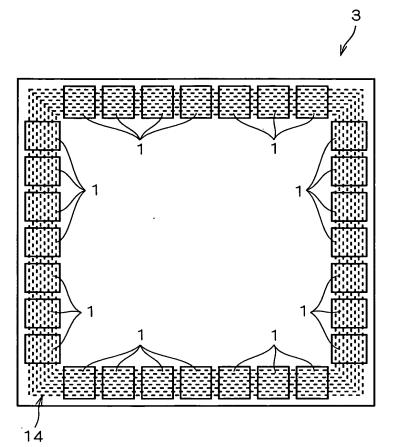


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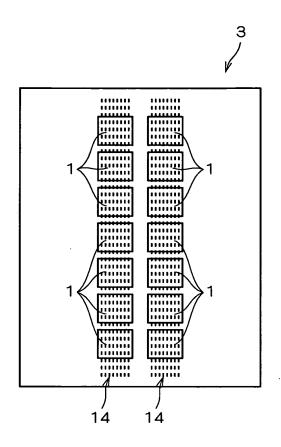


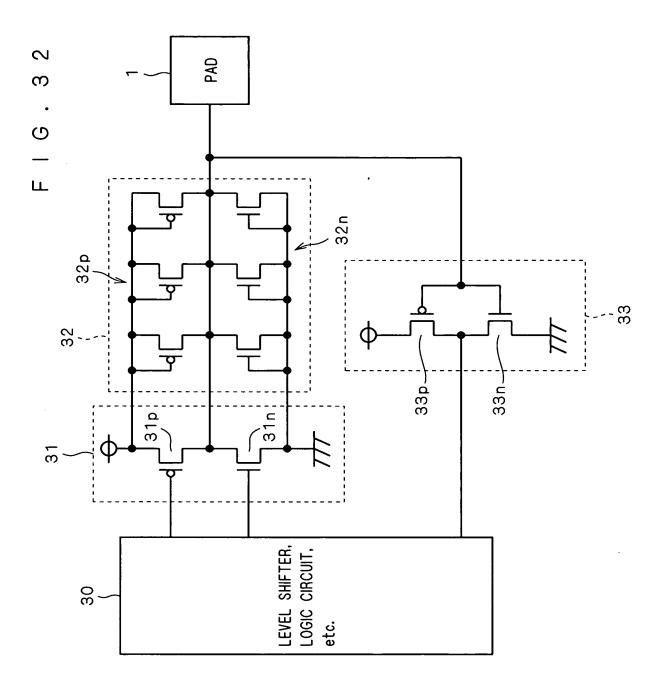
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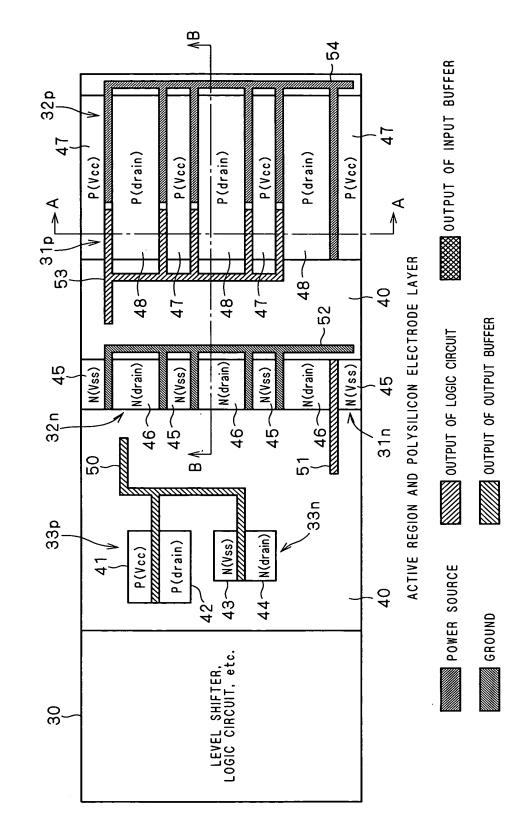




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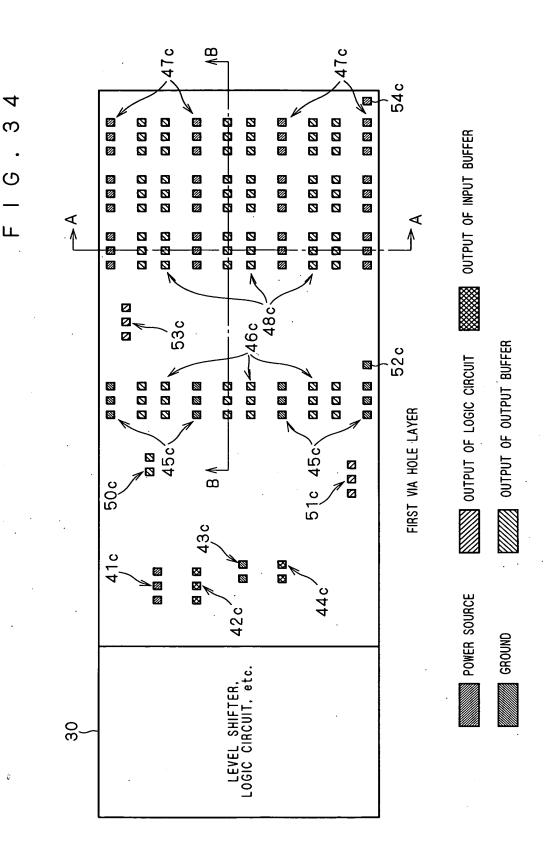


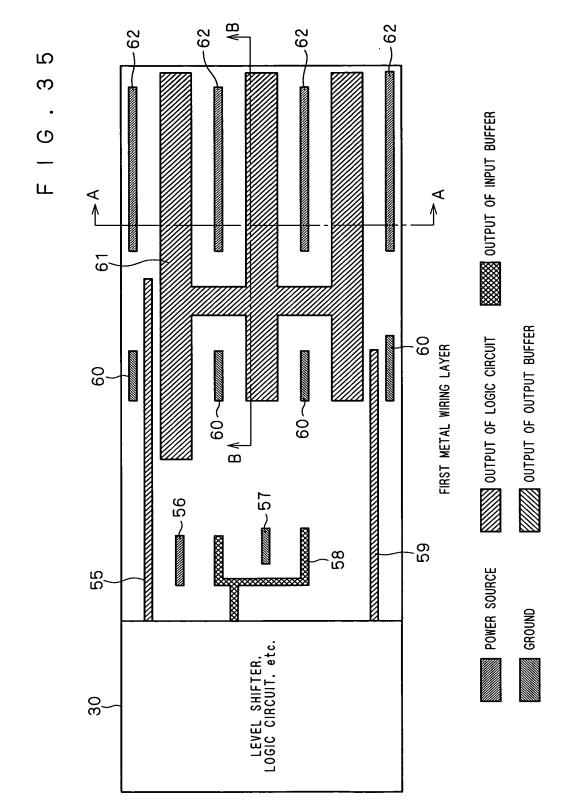


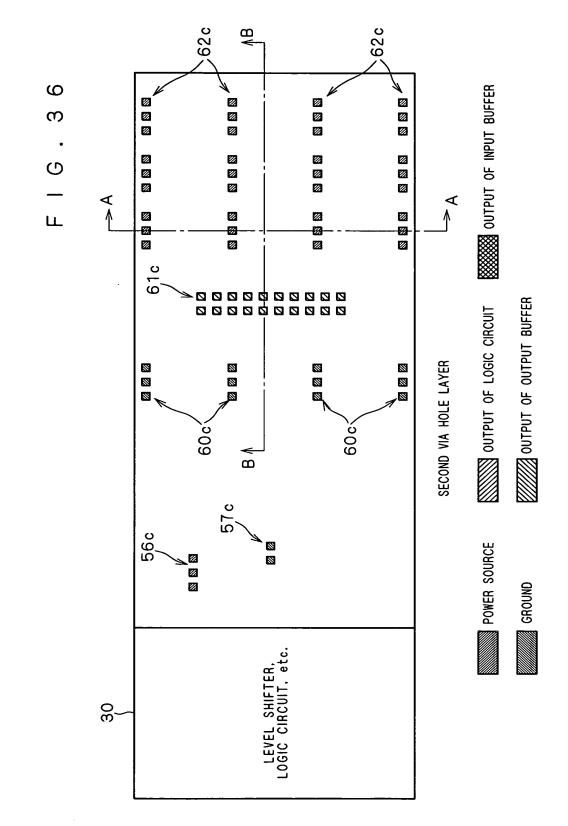
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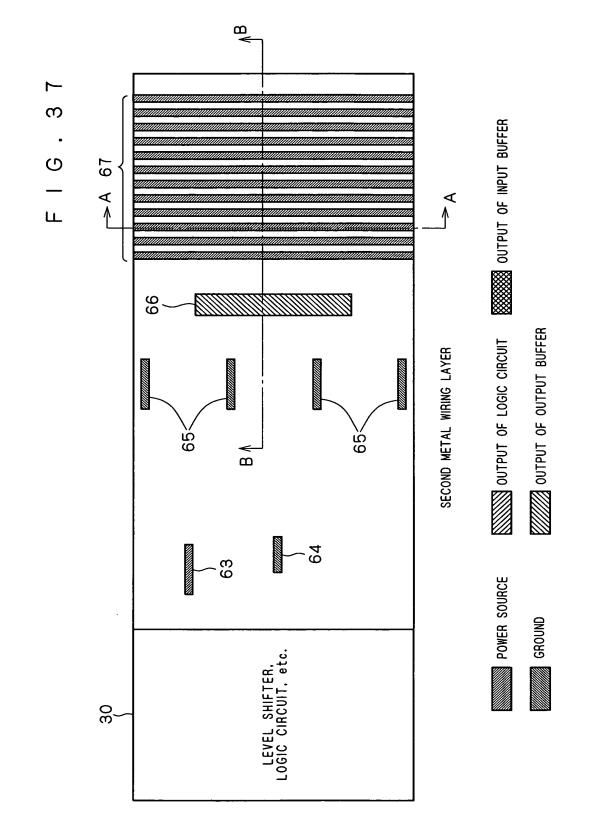
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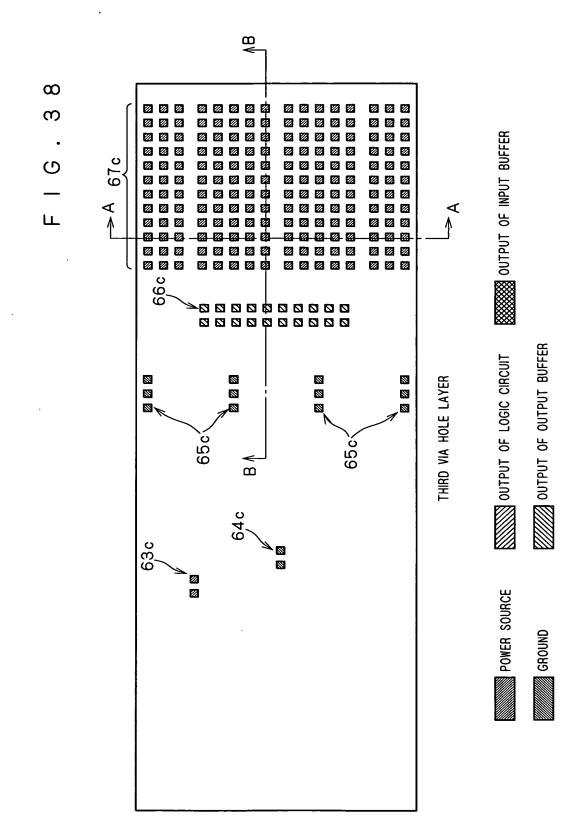
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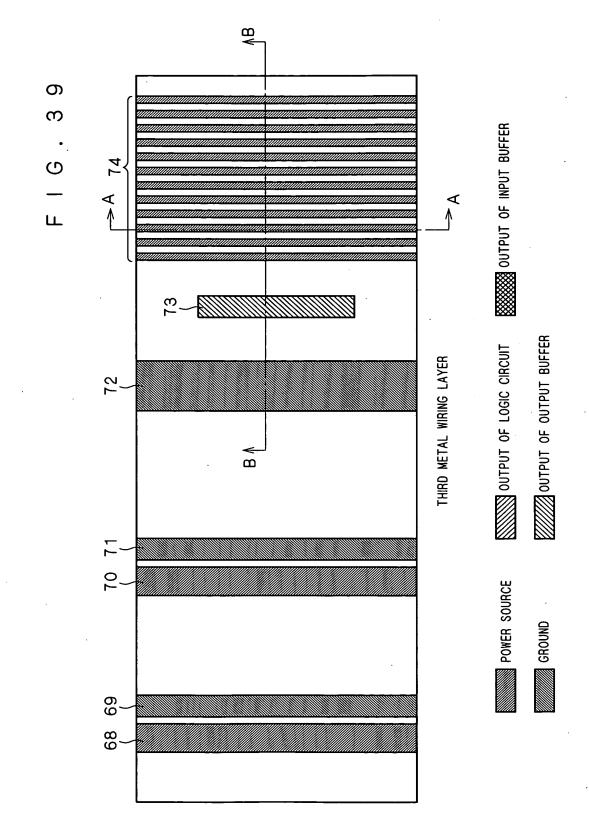


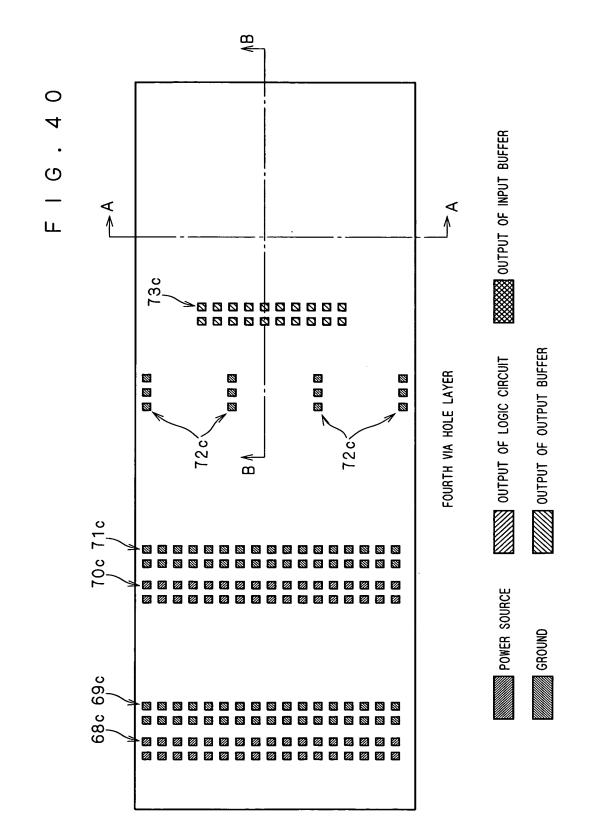


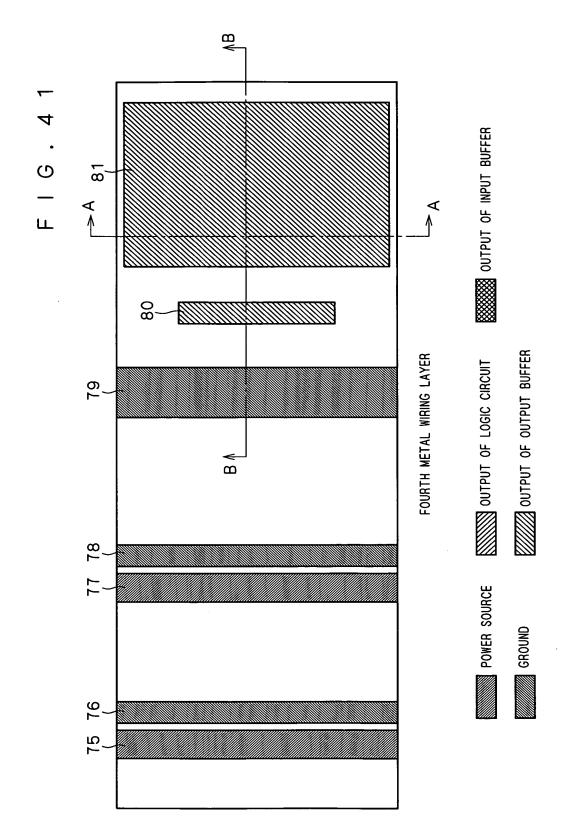


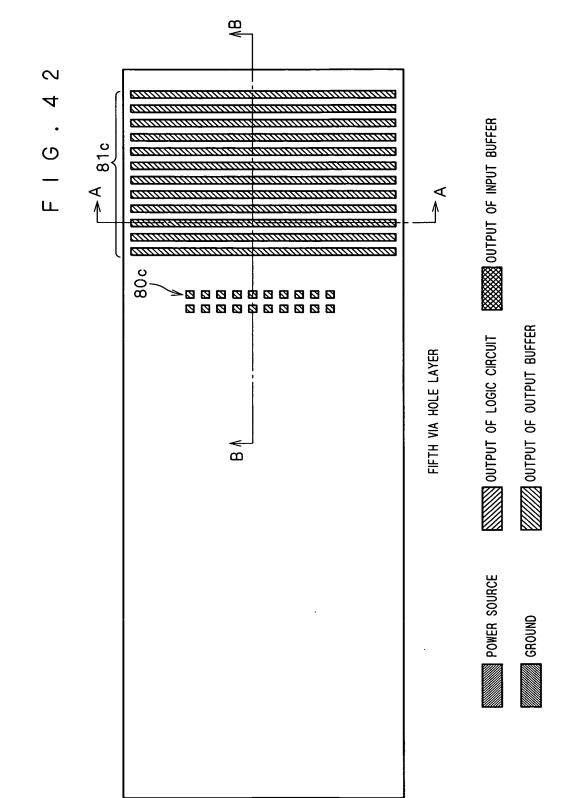


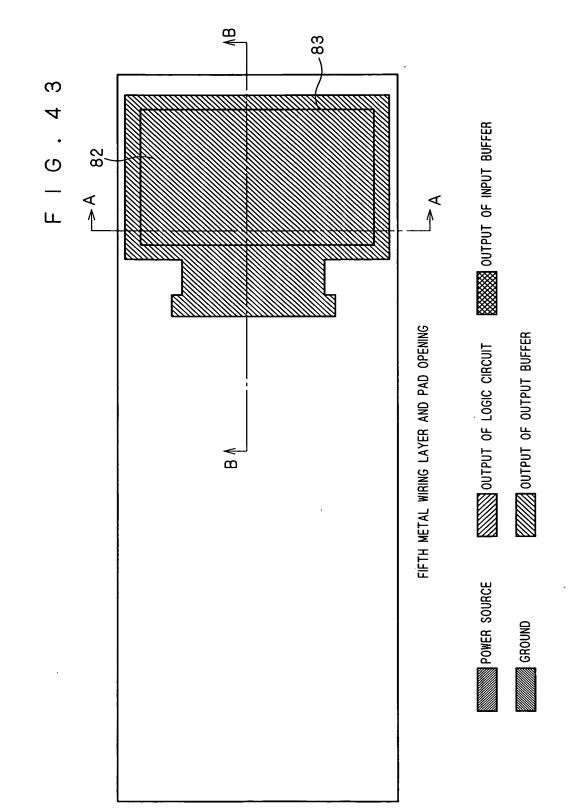


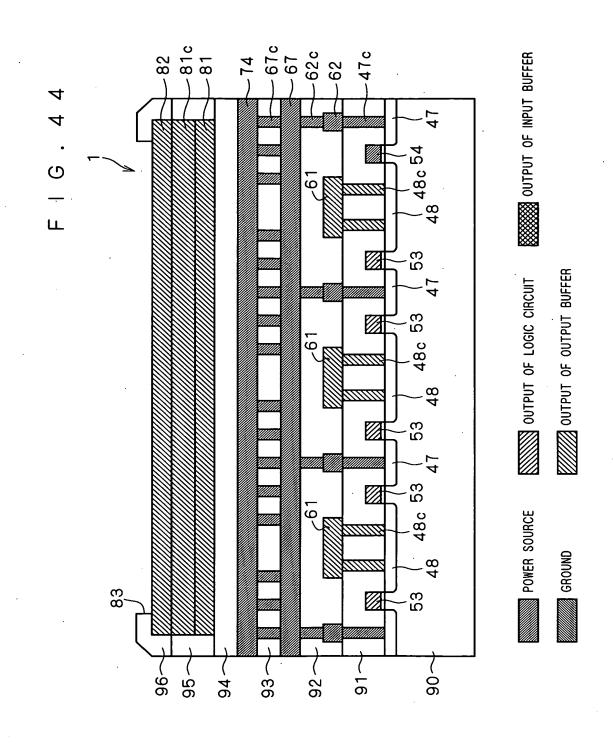


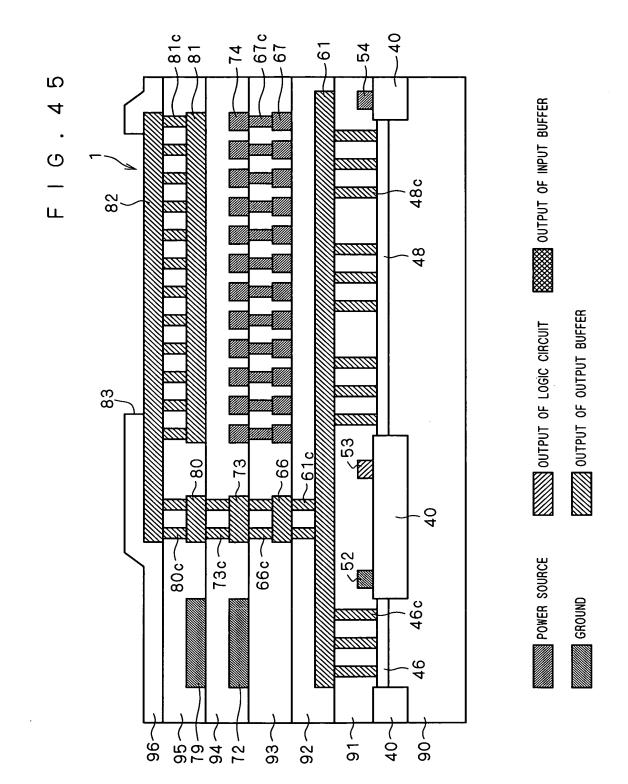


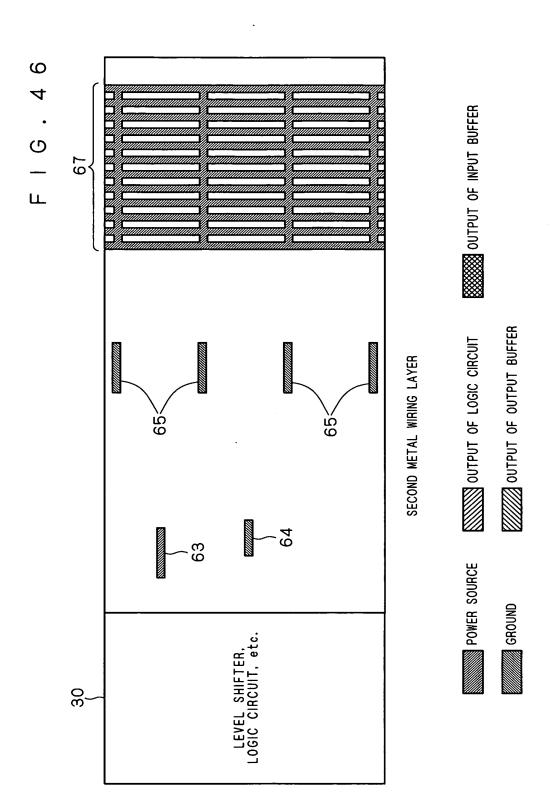


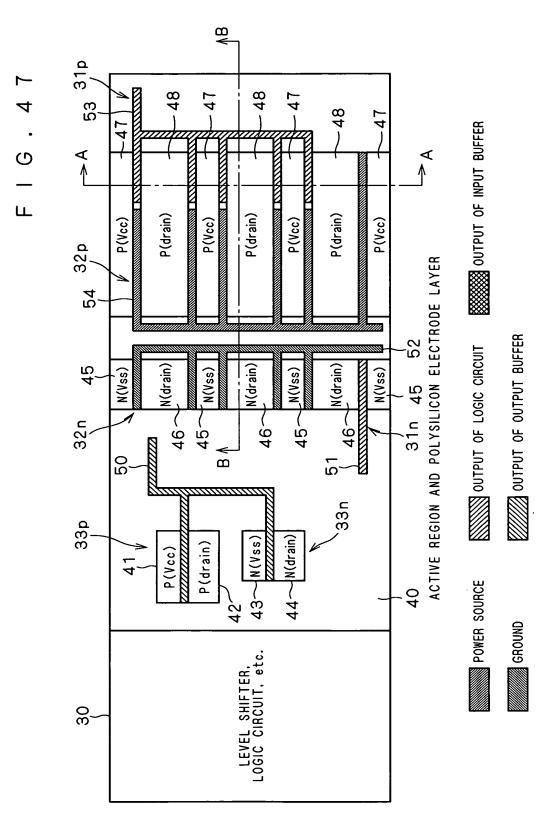


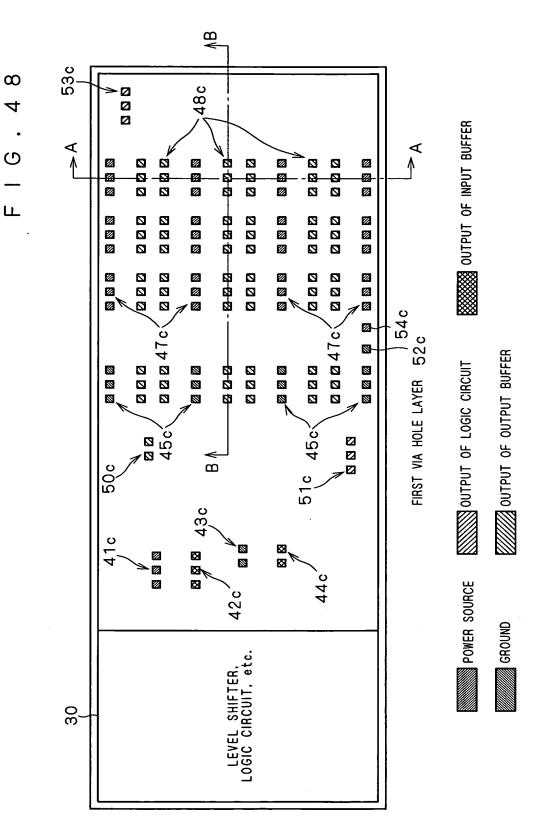


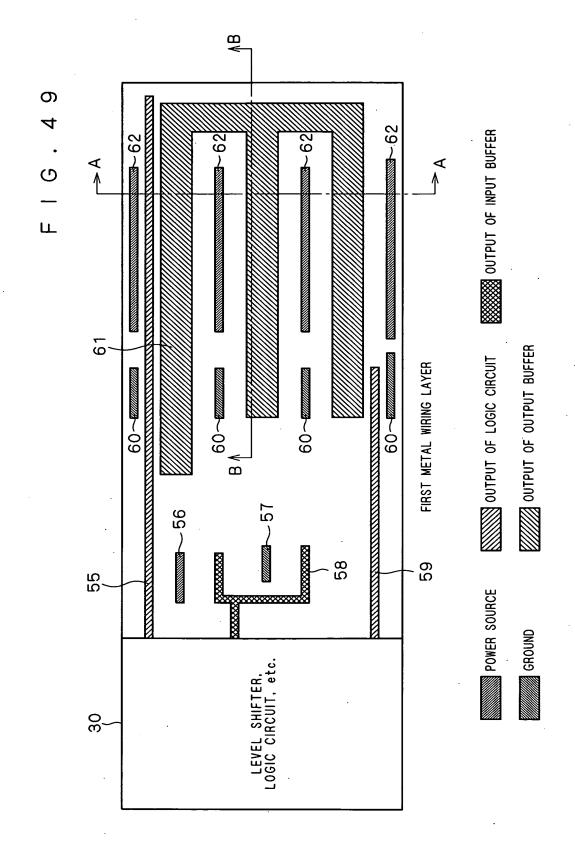


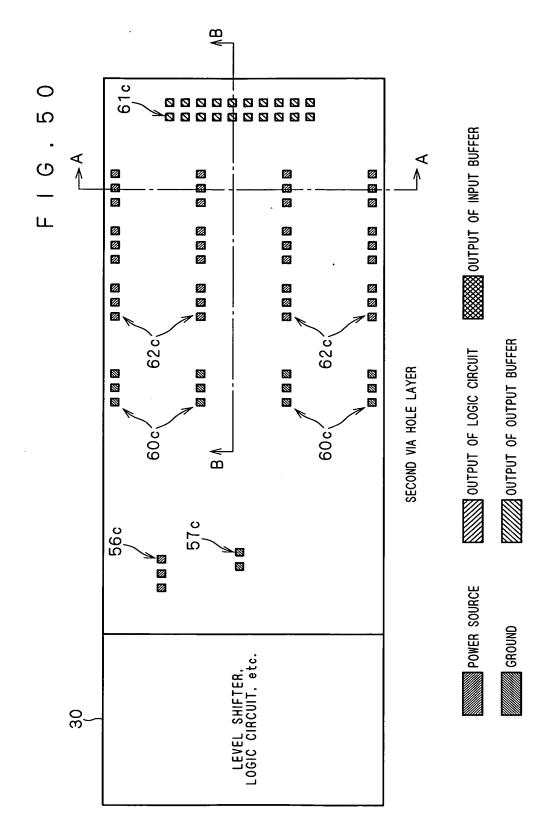


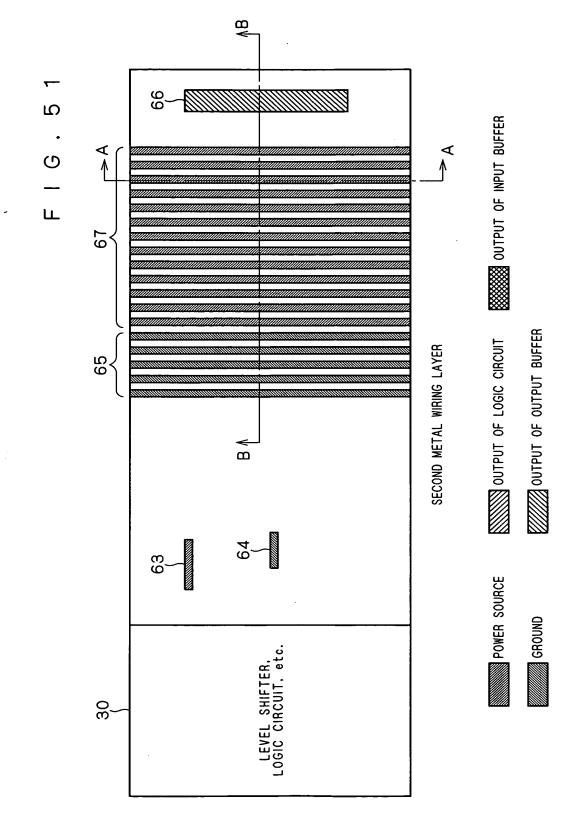


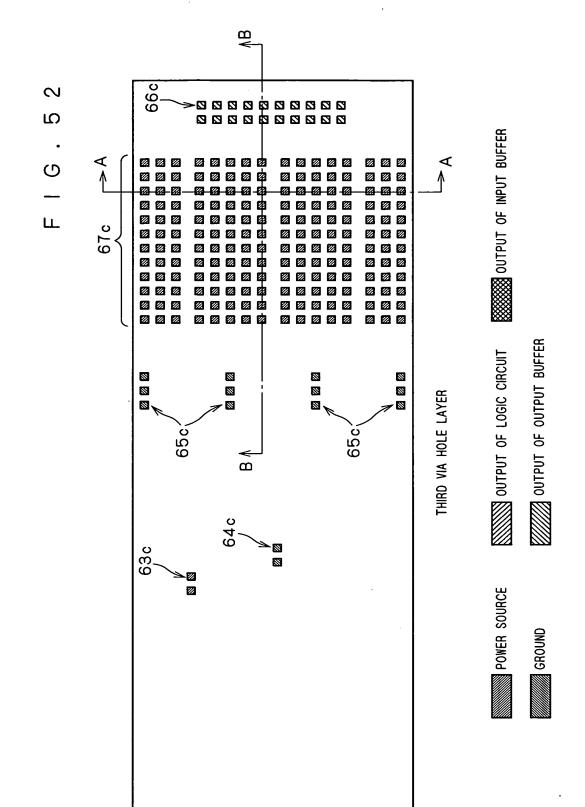


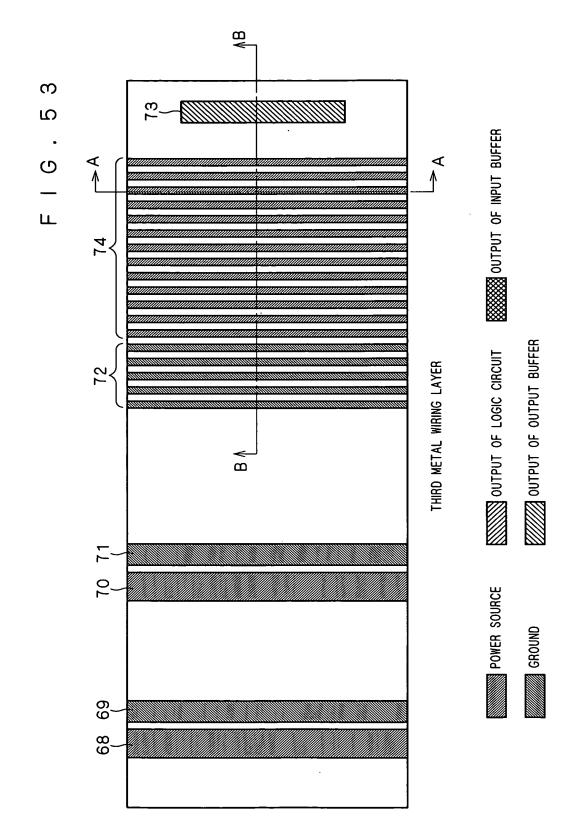


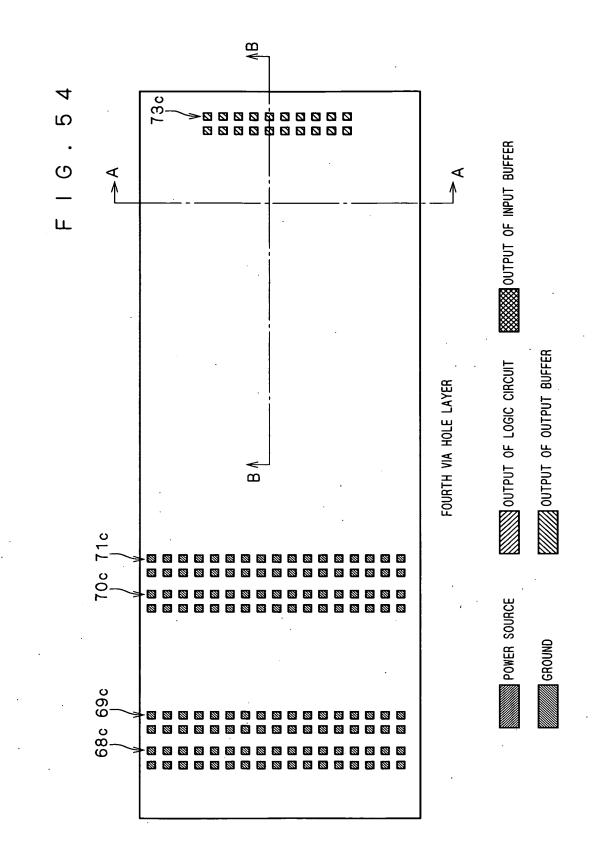


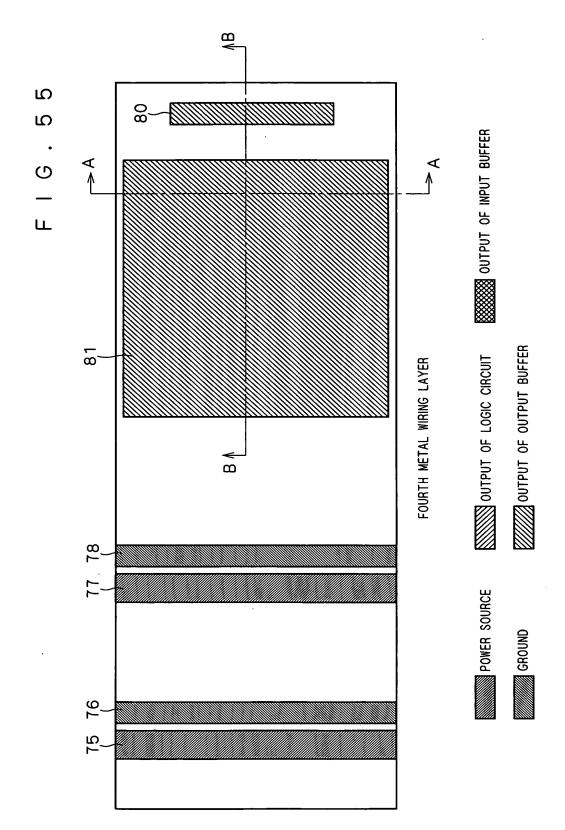


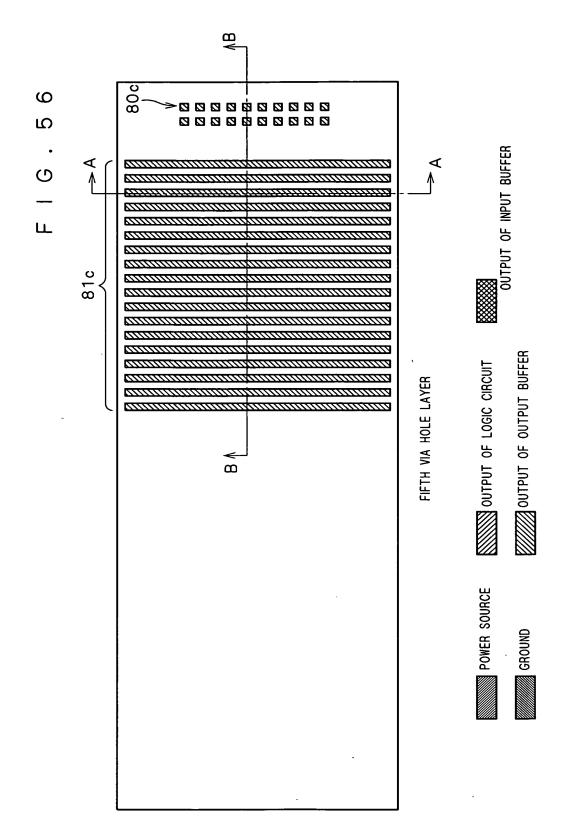


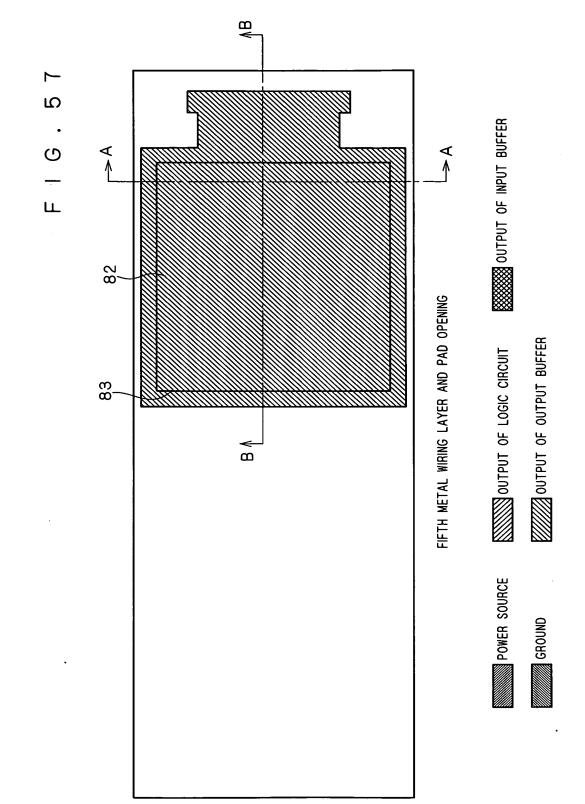


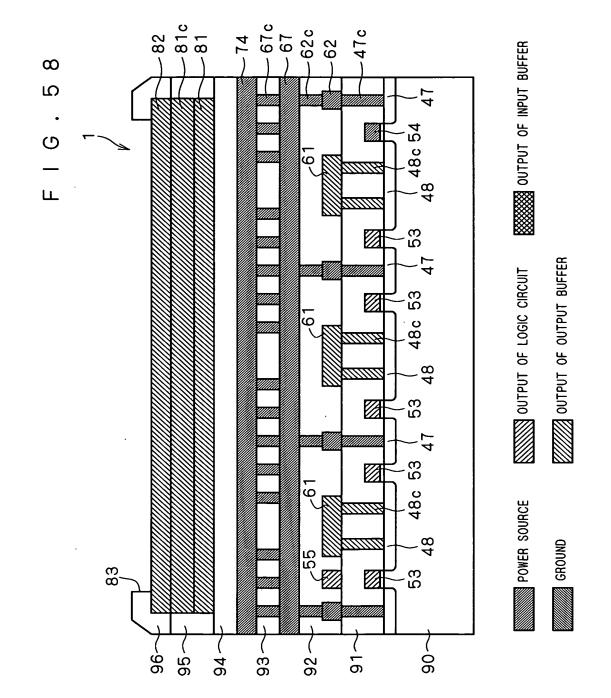


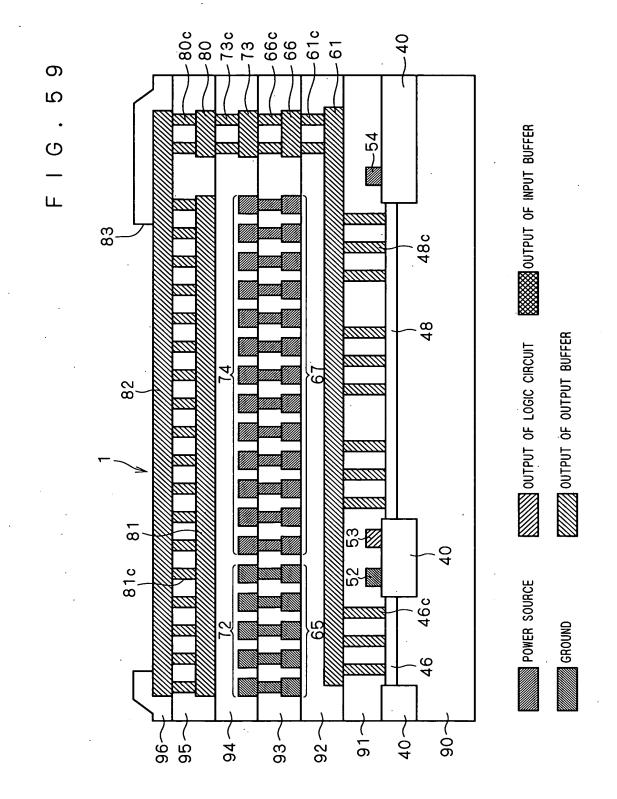


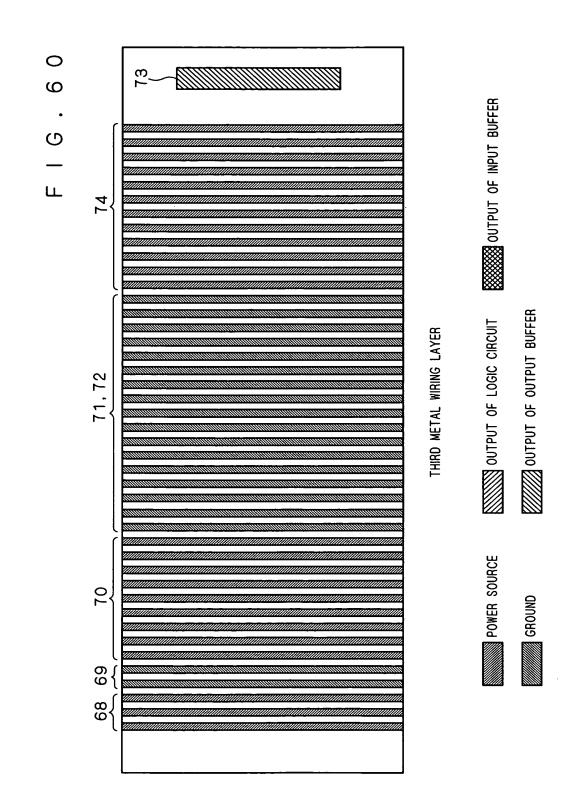


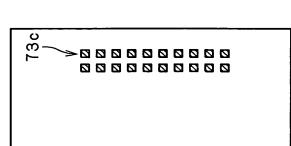












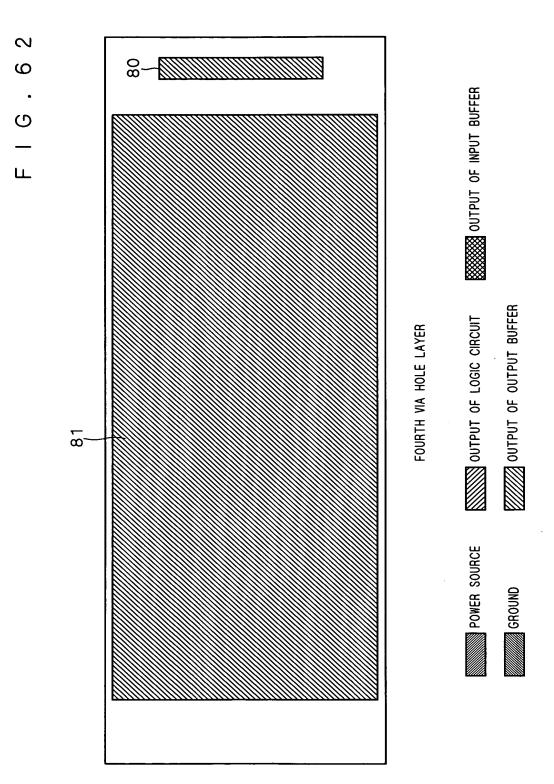
FOURTH VIA HOLE LAYER

OUTPUT OF LOGIC CIRCUIT POWER SOURCE

OUTPUT OF INPUT BUFFER

GROUND

OUTPUT OF OUTPUT BUFFER

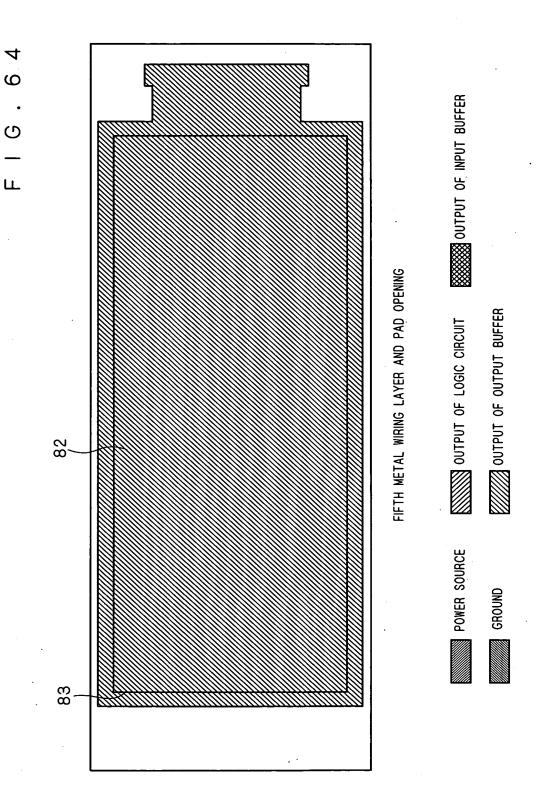


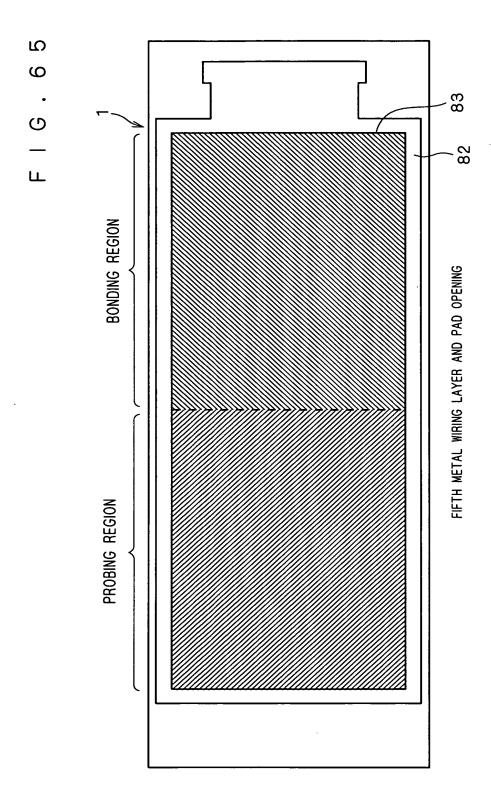
© © © © © © © © © € © © © © © © © © © © OUTPUT OF OUTPUT BUFFER OUTPUT OF LOGIC CIRCUIT POWER SOURCE

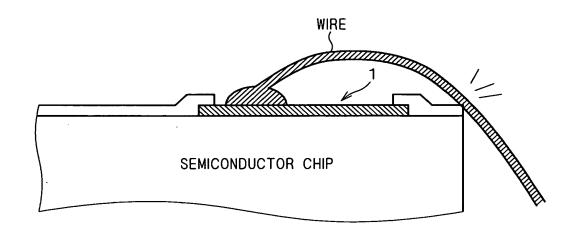
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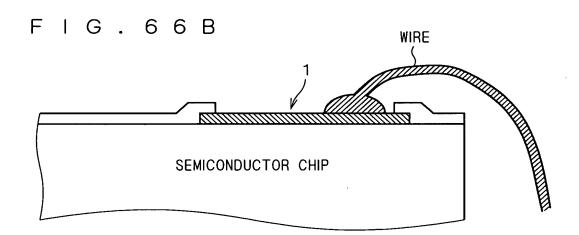
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